

STS17NF3LL

N-CHANNEL 30V - 0.0045 Ω - 17A SO-8 STripFETTM II MOSFET FOR DC-DC CONVERSION

TYPE	PE V _{DSS} R _{DS(on)}		I _D
STS17NF3LL	30 V	<0.0055 Ω	17 A

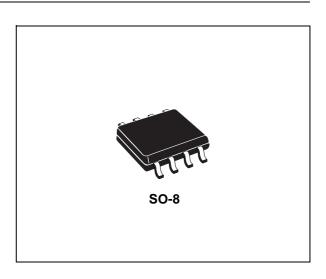
- TYPICAL $R_{DS}(on) = 0.0045 \Omega @ 10V$
- OPTIMAL R_{DS}(on) x Qg TRADE-OFF @ 4.5V
- CONDUCTION LOSSES REDUCED
- SWITCHING LOSSES REDUCED

DESCRIPTION

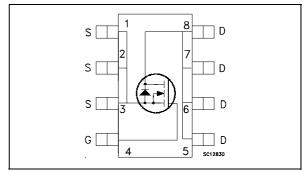
This application specific Power MOSFET is the second generation of STMicroelectronis unique "Single Feature Size™" strip-based process. The resulting transistor shows the best trade-off between on-resistance and gate charge. Such features make it the best choice in high efficiency DC-DC converters for Telecom and computer industries.

APPLICATIONS

- DC-DC CONVERTERS FOR TELECOM AND NOTEBOOK CPU CORE
- SYNCHRONOUS RECTIFIER



INTERNAL SCHEMATIC DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{DS}	Drain-source Voltage (V _{GS} = 0)	30	V
V _{DGR}	Drain-gate Voltage ($R_{GS} = 20 \text{ k}\Omega$)	30	V
V _{GS}	Gate- source Voltage	± 18	V
I _D	Drain Current (continuous) at T _C = 25°C	17	А
I _D	Drain Current (continuous) at T _C = 100°C	12	А
I _{DM} (•)	Drain Current (pulsed)	68	А
P _{tot}	Total Dissipation at T _C = 25°C	3.2	W

^(•) Pulse width limited by safe operating area.

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THERMAL DATA

Rthj-amb Rthj-lead T _j T _{stq}	(*)Thermal Resistance Junction-ambient Thermal Resistance Junction-leads Maximum Operating Junction Temperature Storage Temperature	Max Max	47 16 -55 to 175 -55 to 175	°C/W °C °C °C
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^(*) When Mounted on 1 inch² FR-4 board, 2 oz of Cu and t \leq 10 sec.

ELECTRICAL CHARACTERISTICS (T_{case} = 25 °C unless otherwise specified)

OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source Breakdown Voltage	$I_D = 250 \ \mu A, \ V_{GS} = 0$	30			V
I _{DSS}	Zero Gate Voltage Drain Current (V _{GS} = 0)	$V_{DS} = Max Rating$ $V_{DS} = Max Rating T_C = 125^{\circ}C$			1 10	μA μA
I _{GSS}	Gate-body Leakage Current (V _{DS} = 0)	V _{GS} = ± 18 V			±100	nA

ON (*)

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}$	$I_D = 250 \mu A$	1			V
R _{DS(on)}	Static Drain-source On Resistance	V _{GS} = 10 V V _{GS} = 4.5 V	I _D = 8.5 A I _D = 8.5 A		0.0045 0.0055	0.0055 0.007	Ω Ω

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
g _{fs} (*)	Forward Transconductance	$V_{DS} = 10 \text{ V}$ $I_{D} = 8.5 \text{ A}$		37		S
C _{iss} C _{oss} C _{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25V$, $f = 1 MHz$, $V_{GS} = 0$		2160 614 98		pF pF pF

ELECTRICAL CHARACTERISTICS (continued)

SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{d(on)} t _r	Turn-on Delay Time Rise Time	$\begin{aligned} V_{DD} &= 15 \text{ V} & I_D &= 8.5 \text{ A} \\ R_G &= 4.7 \Omega & V_{GS} &= 4.5 \text{ V} \\ \text{(Resistive Load, Figure 1)} \end{aligned}$		23.5 39		ns ns
Q _g Q _{gs} Q _{gd}	Total Gate Charge Gate-Source Charge Gate-Drain Charge	V_{DD} =24V I_{D} =12.5A V_{GS} =4.5 V (see test circuit, Figure 2)		26 7 12	35	nC nC nC

SWITCHING OFF

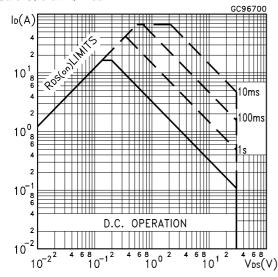
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t _{d(off)} t _f	Turn-off Delay Time Fall Time	$\begin{aligned} &V_{DD} = 15 \text{ V} & I_{D} = 8.5 \text{ A} \\ &R_{G} = 4.7 \Omega, & V_{GS} = 4.5 \text{ V} \\ &(\text{Resistive Load, Figure 3}) \end{aligned}$		47.5 37		ns ns

SOURCE DRAIN DIODE

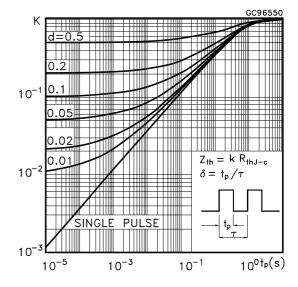
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
I _{SD} I _{SDM} (•)	Source-drain Current Source-drain Current (pulsed)				17 68	A A
V _{SD} (*)	Forward On Voltage	I _{SD} = 17 A V _{GS} = 0			1.2	V
t _{rr} Q _{rr} I _{RRM}	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	I_{SD} = 17 A di/dt = 100A/ μ s V_{DD} = 15 V T_j = 150°C (see test circuit, Figure 3)		39 45 2.3		ns nC A

^(*)Pulsed: Pulse duration = 300 µs, duty cycle 1.5 %.
(•)Pulse width limited by safe operating area.

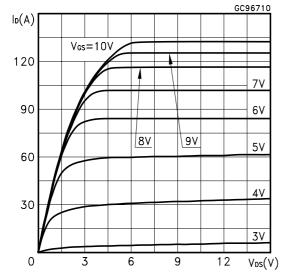
Safe Operating Area



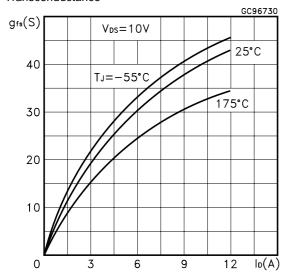
Thermal Impedance



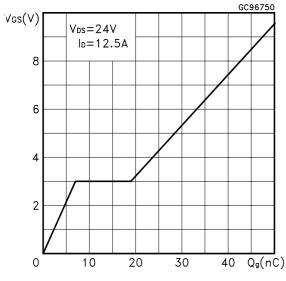
Output Characteristics



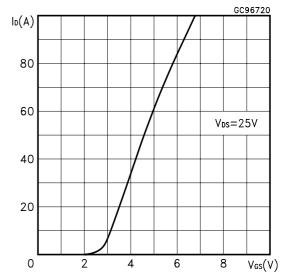
Transconductance



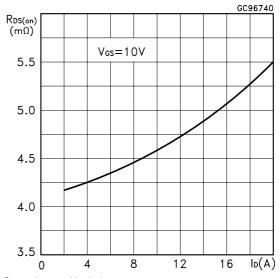
Gate Charge vs Gate-source Voltage



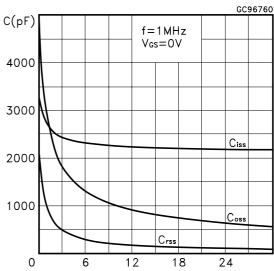
Transfer Characteristics



Static Drain-source On Resistance

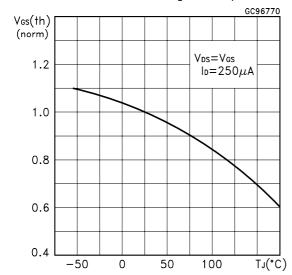


Capacitance Variations

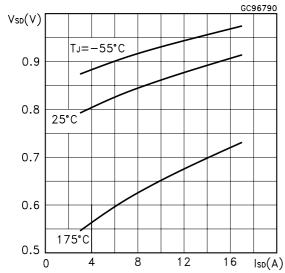


47/

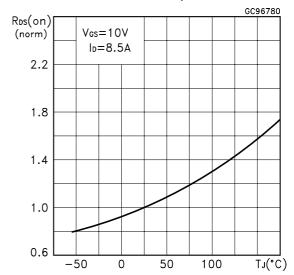
Normalized Gate Threshold Voltage vs Temperature



Source-drain Diode Forward Characteristics



Normalized on Resistance vs Temperature



Normalized Breakdown Voltage vs Temperature.

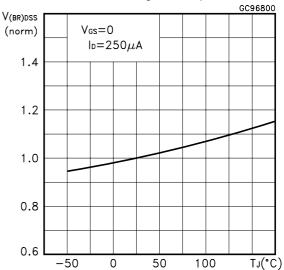


Fig. 1: Switching Times Test Circuits For Resistive Load

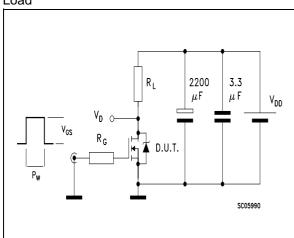


Fig. 2: Gate Charge test Circuit

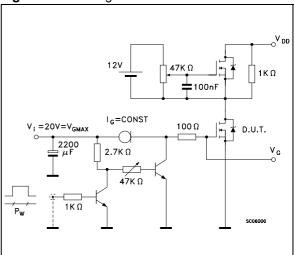
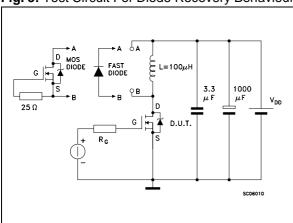
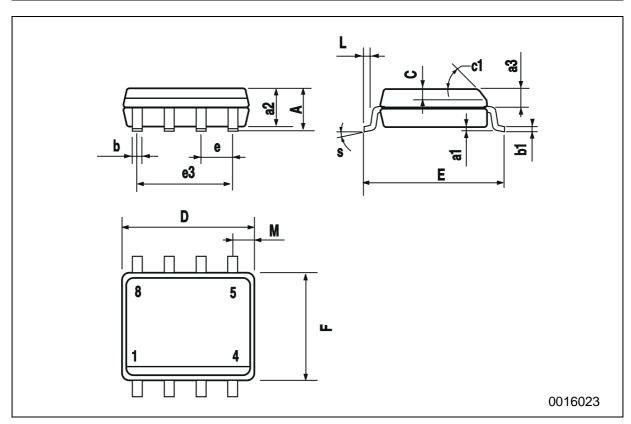


Fig. 3: Test Circuit For Diode Recovery Behaviour



SO-8 MECHANICAL DATA

DIM.		mm			inch	
DIIVI.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А			1.75			0.068
a1	0.1		0.25	0.003		0.009
a2			1.65			0.064
a3	0.65		0.85	0.025		0.033
b	0.35		0.48	0.013		0.018
b1	0.19		0.25	0.007		0.010
С	0.25		0.5	0.010		0.019
c1			45	(typ.)		
D	4.8		5.0	0.188		0.196
Е	5.8		6.2	0.228		0.244
е		1.27			0.050	
e3		3.81			0.150	
F	3.8		4.0	0.14		0.157
L	0.4		1.27	0.015		0.050
М			0.6			0.023
S			8 (r	nax.)		



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